

N-Channel 100V MOSFET

Product summary

V_{DS} (V)	$R_{DS(on),max}$ (m Ω)	I_D (A)
100	2.1 @ $V_{GS} = 10V$	176 ⁽¹⁾

Features

- Low $R_{DS(on)}$ trench technology
- Low thermal impedance
- Fast switching speed
- 100% avalanche tested

Applications

- DC/DC conversion
- Power switch
- Motor drives

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Package and ordering information

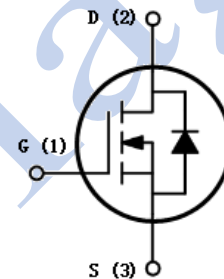
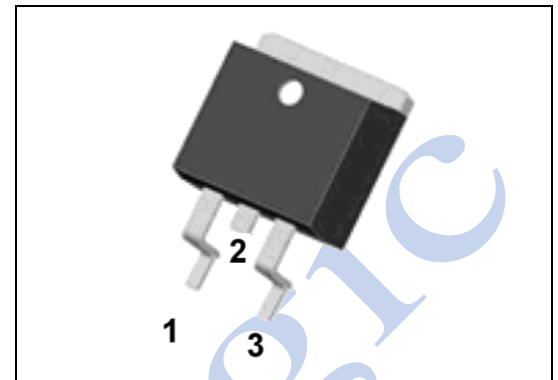
Ordering code	Package	Device code
SDH10N2P1S2B	TO263-3L	ADQ

1. Maximum ratings

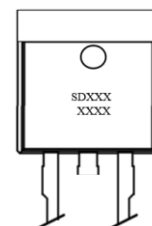
Absolute maximum ratings ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Parameter		Symbol	Limit	Unit
Drain-source voltage		V_{DS}	100	V
Gate-source voltage		V_{GS}	± 20	
Continuous drain current	$T_C = 25^\circ\text{C}$ ⁽¹⁾	I_D	176	A
	$T_C = 100^\circ\text{C}$ ⁽¹⁾		176	
	$T_A = 25^\circ\text{C}$ ⁽⁴⁾		29.5	
Pulsed drain current ⁽²⁾		$I_{D,pulse}$	704	
Avalanche energy, single pulse ⁽³⁾		E_{AS}	1750	mJ
Power dissipation	$T_C = 25^\circ\text{C}$	P_D	357	W
	$T_A = 25^\circ\text{C}$ ⁽⁴⁾		3.7	
Operating junction and storage temperature range		T_J, T_{stg}	-55 to 175	$^\circ\text{C}$

TO263-3L



RoHS
COMPLIANT
HALOGEN
FREE



SDXXXX
Device code
Silicon Magic discrete device
XXXX
Wafer lot number
Work week code
Year code

2. Thermal resistance ratings

Thermal resistance ratings						
Parameter		Symbol	Max.	Unit		
Thermal resistance, junction-to-case	Steady state	$R_{\theta JC}$	0.42			°C/W
Thermal resistance, junction-to-ambient ⁽⁴⁾	Steady state	$R_{\theta JA}$	40			

3. Electrical characteristics

Electrical characteristics (T _J = 25°C unless otherwise noted)						
Parameter	Symbol	Test conditions	Min.	Typ.	Max.	Unit
Static parameter						
Drain to source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 1 mA	100			V
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	2.2	3	3.8	V
Gate-body leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±20 V			±100	nA
Zero gate voltage drain current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V			1	μA
Drain-source on-resistance	R _{DS(on)}	V _{GS} = 10 V, I _D = 100 A		1.6	2.1	mΩ
Forward transconductance ⁽⁵⁾	g _{fs}	V _{DS} = 5 V, I _D = 100 A		270		S
Gate resistance	R _g	f = 1 MHz		1	2	Ω
Dynamic ⁽⁵⁾						
Total gate charge	Q _g	V _{DS} = 50 V, I _D = 100 A, V _{GS} = 10 V		245		nC
Gate-source charge	Q _{gs}			70		
Gate-drain charge	Q _{gd}			65		
Turn-on delay time	t _{d(on)}	V _{DS} = 50 V, I _D = 100 A, V _{GS} = 10 V, R _{GEN} = 6 Ω		65		ns
Rise time	t _r			139		
Turn-off delay time	t _{d(off)}			141		
Fall time	t _f			66		
Input capacitance	C _{iss}	V _{DS} = 50 V, V _{GS} = 0 V, f = 1 MHz		15580		pF
Output capacitance	C _{oss}			2070		
Reverse transfer capacitance	C _{rss}			55		
Reverse Diode Characteristics ⁽⁵⁾						
Diode forward voltage	V _{SD}	V _{GS} = 0 V, I _F = 100 A		0.9	1.2	V
Reverse recovery time	t _{rr}	V _{DS} = 50 V, I _F = 100 A, di/dt = 100 A/μs		99		ns
Reverse recovery charge	Q _{rr}			258		nC

Notes

- (1) Package limited.
- (2) Pulse width limited by maximum junction temperature.
- (3) $V_{DS} = 75\text{ V}, V_{GS} = 10\text{ V}, L = 0.3\text{ mH}$.
- (4) $R_{\theta JA}$ is determined with the device mounted on a 1 in² pad 2 oz copper pad on a 1.5x1.5 in. board of FR-4 material.
- (5) Guaranteed by design, not subject to production testing.

4. Electrical characteristics diagrams

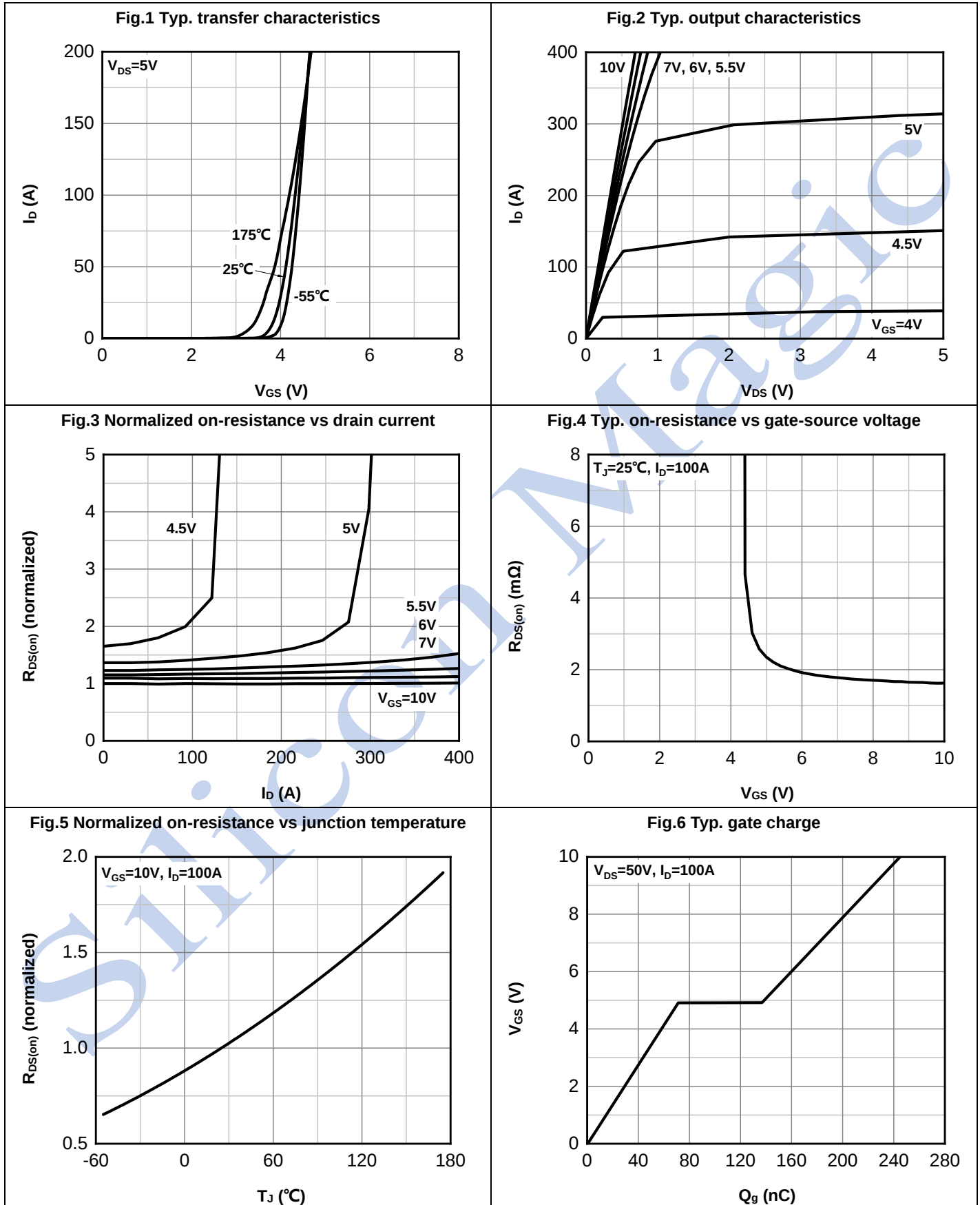


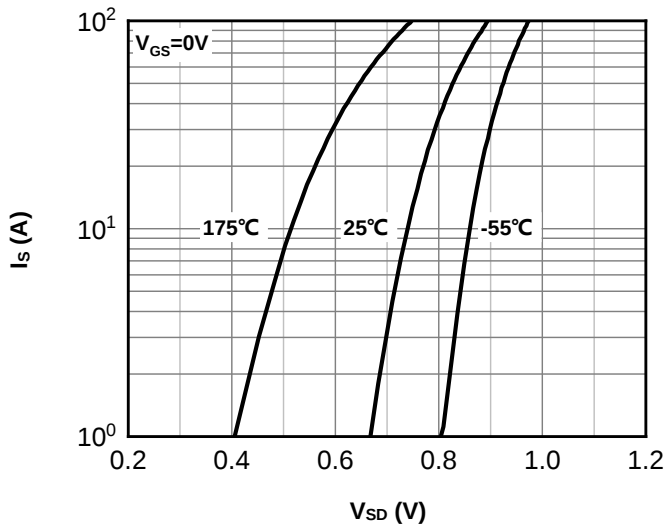
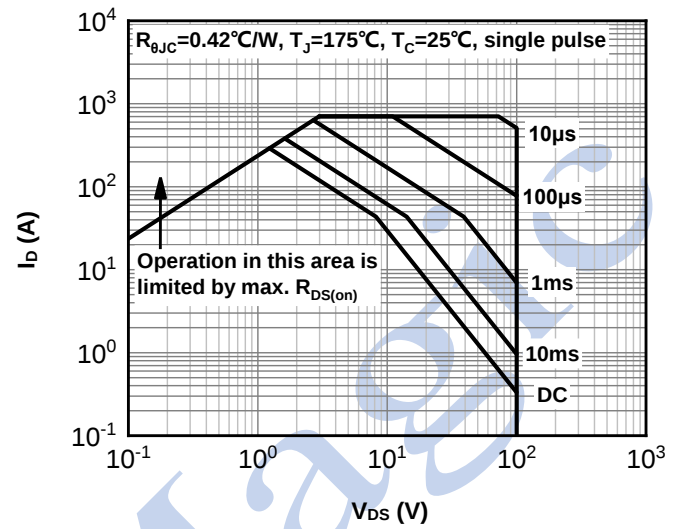
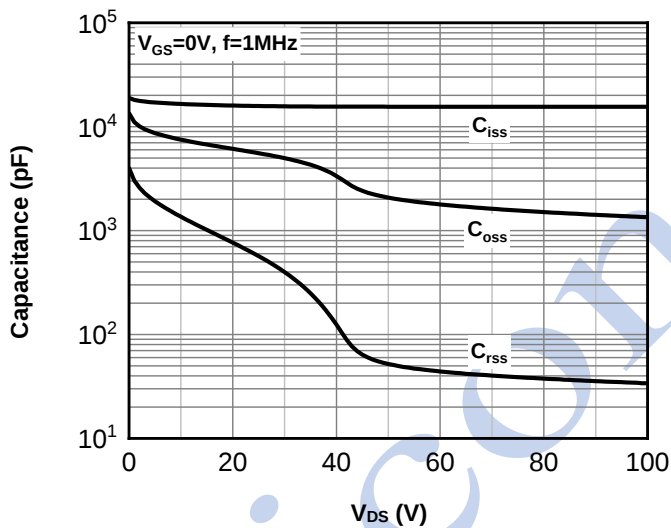
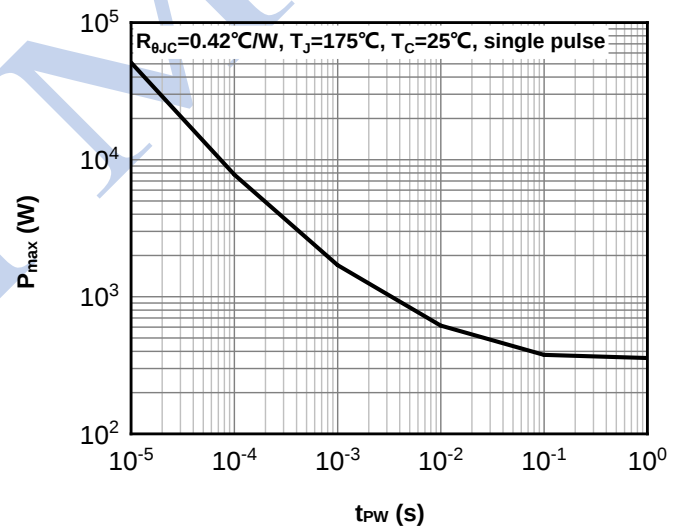
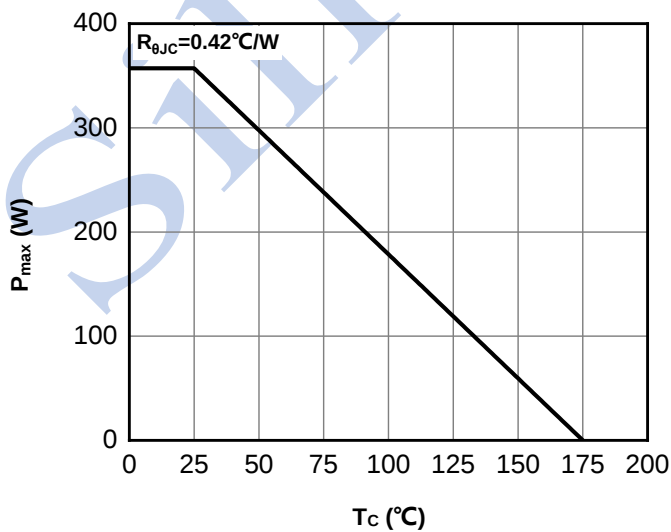
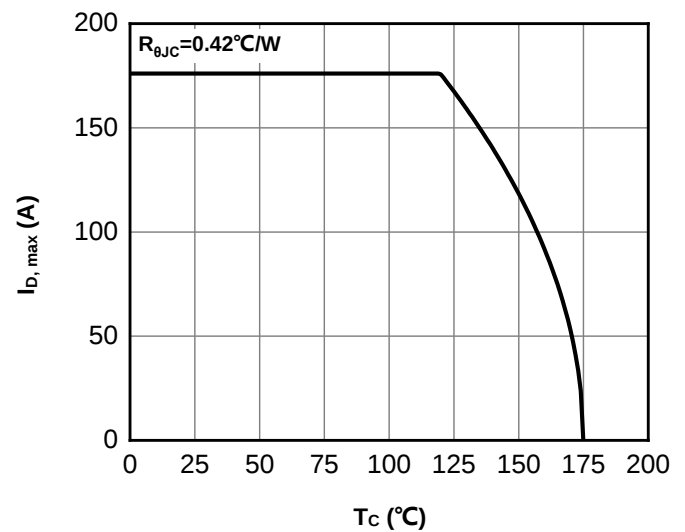
Fig.7 Typ. forward characteristics of body diode

Fig.8 Safe operating area

Fig.9 Typ. Capacitance

Fig.10 Single pulse maximum power dissipation

Fig.11 Max. power dissipation vs case temperature

Fig.12 Max. continuous drain current vs case temperature


Fig.13 Normalized $V_{(BR)DSS}$ vs junction temperature

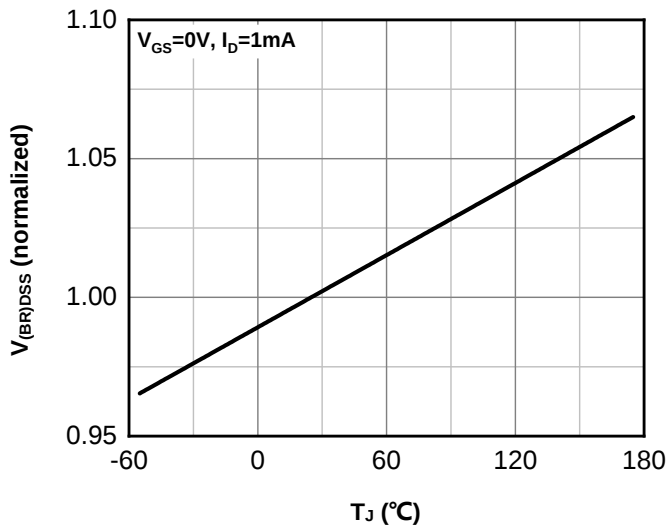


Fig.14 Normalized $V_{GS(th)}$ vs junction temperature

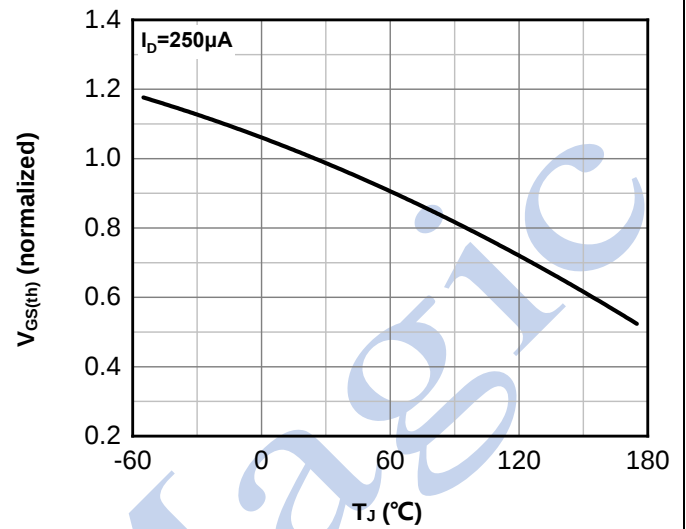
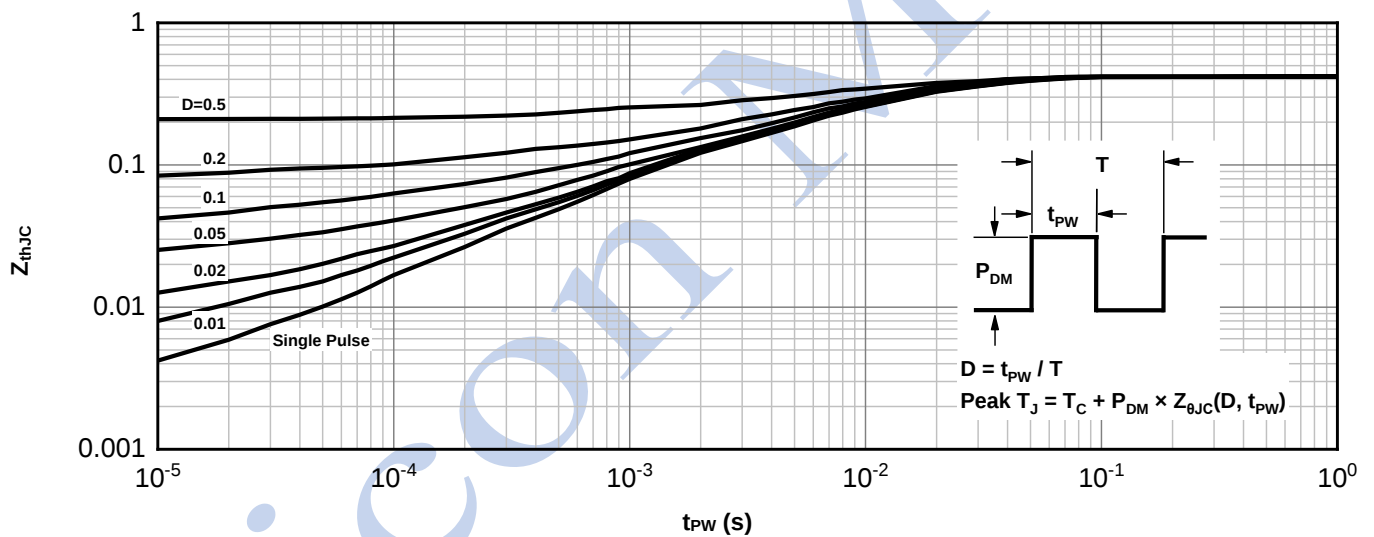
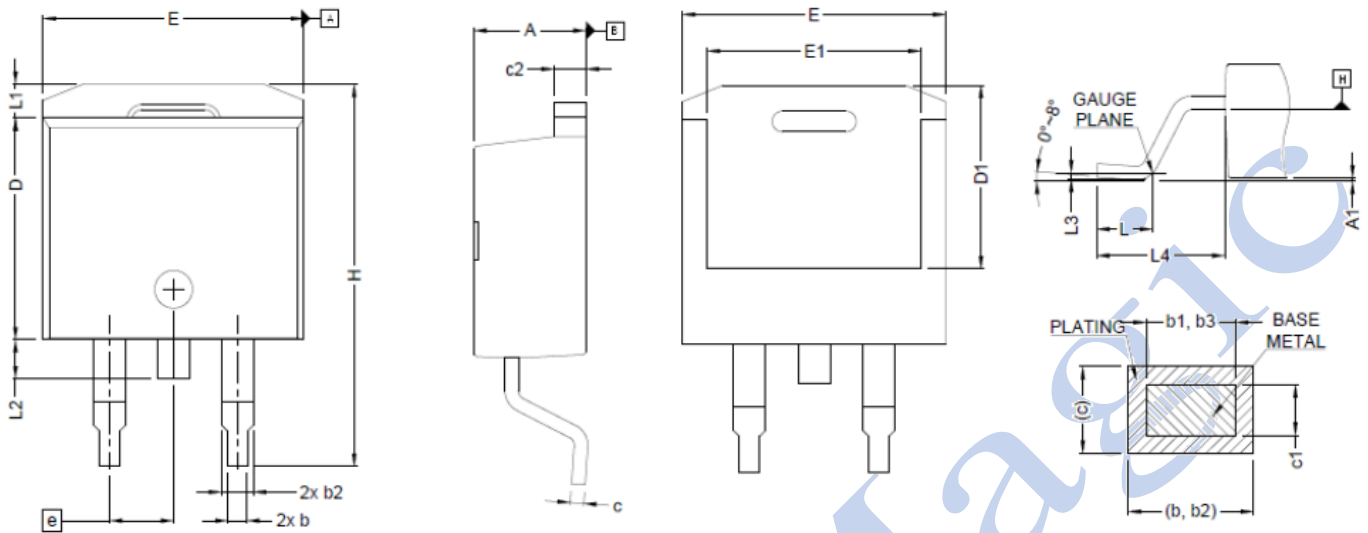


Fig.15 Transient thermal impedance from junction to case



5. Package outline dimensions



	Millimeters		
	Min	Nom	Max
A	4.36	-	4.56
A1	0.00	-	0.25
b	0.70	-	0.90
b1	0.51	-	0.89
b2	1.17	-	1.37
b3	1.17	-	1.37
c	0.38	-	0.69
c1	0.38	-	0.53
c2	1.19	-	1.34
D	8.60	-	9.00
D1	6.90	-	7.50
E	10.15	-	10.55
E1	8.10	-	8.70
e	2.54 BSC		
H	15.00	-	15.60
L	1.90	-	2.50
L1	-	-	1.65
L2	-	-	1.78
L3	0.25TYP		
L4	4.78	-	5.28
J1	2.56	-	2.96

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